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- 5-Ω Switch Connection Between Two Ports
- TTL-Compatible Input Levels
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- Package Options Include Plastic Thin Shrink Small-Outline (DGG), Thin Very Small-Outline (DGV), and 300-mil Shrink Small-Outline (DL) Packages

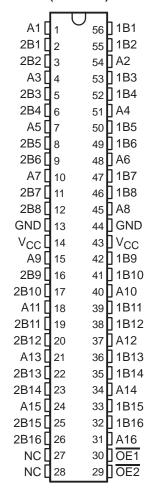
description

The SN74CBT16390 is a 16-bit to 32-bit switch used in applications in which two separate data paths must be multiplexed onto, or demultiplexed from, a single path. This device can be used for memory interleaving, in which two different banks of memory must be addressed simultaneously. This also can be used to connect or isolate the PCI bus to one or two slots simultaneously.

Two output enables ($\overline{OE1}$ and $\overline{OE2}$) control the data flow. When $\overline{OE1}$ is low, A port is connected to 1B port. When $\overline{OE2}$ is low, A port is connected to 2B port. When both $\overline{OE1}$ and $\overline{OE2}$ are low, the A port is connected to both 1B and 2B ports. The control inputs can be driven with a 5-V CMOS, 5-V TTL, or an LVTTL driver.

The SN74CBT16390 is characterized for operation from –40°C to 85°C.

DGG, DGV, OR DL PACKAGE (TOP VIEW)



NC - No internal connection

FUNCTION TABLE

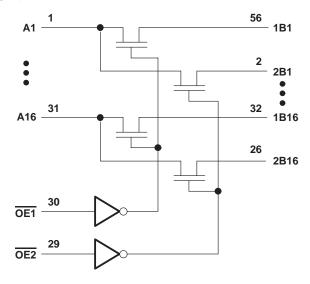
INPUTS		FUNCTION				
OE1	OE2	FUNCTION				
L	L	A = 1B and A = 2B				
L	Н	A = 1B				
Н	L	A = 2B				
Н	Н	Isolation				



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logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}		–0.5 V to 7 V
Input voltage range, V _I (see Note 1)		0.5 V to V _{CC} + 0.5 V
Continuous channel current		128 mA
Input clamp current, I_{IK} ($V_I < 0$)		–50 mA
Package thermal impedance, θ_{JA} (see Note 2):	: DGG package	81°C/W
	DGV package	86°C/W
	DL package	74°C/W
Storage temperature range, T _{stg}		–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions (see Note 3)

		MIN	MAX	UNIT
VCC	Supply voltage	4.5	5.5	V
VIH	High-level control input voltage	2		V
V _{IL}	Low-level control input voltage		0.8	V
TA	Operating free-air temperature	-40	85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

^{2.} The package thermal impedance is calculated in accordance with JESD 51.

SN74CBT16390 16-BIT TO 32-BIT FET MULTIPLEXER/DEMULTIPLEXER BUS SWITCH

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PA	RAMETER	METER TEST CONDITIONS		MIN	TYP [†]	MAX	UNIT	
VIK		$V_{CC} = 4.5 \text{ V},$	I _I = -18 mA				-1.2	V
Ч		$V_{CC} = 0$,	V _I = 5.5 V				10	μΑ
		$V_{CC} = 5.5 \text{ V},$	$V_I = 5.5 \text{ V or GND}$				±1	
Icc		$V_{CC} = 5.5 \text{ V},$	$I_{O} = 0,$	$V_I = V_{CC}$ or GND			3	μΑ
Δl _{CC} ‡	Control inputs	$V_{CC} = 5.5 \text{ V},$	One input at 3.4 V,	Other input at V _{CC} or GND			2.5	mA
Ci	Control inputs	V _I = 3 V or 0				5		pF
C _{io(OFF})	$V_O = 3 \text{ V or } 0$				5.5		pF
			V _I = 0	I _I = 64 mA		5	7	
r _{on} §		V _{CC} = 4.5 V	v = 0	I _I = 30 mA		5	7	Ω
			V _I = 2.4 V,	I _I = 15 mA		7	12	

[†] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	MIN	MAX	UNIT
t _{pd} ¶	A or B	B or A		0.25	ns
^t en	ŌĒ	A or B	1.3	5.9	ns
^t dis	ŌĒ	A or B	1	5.3	ns

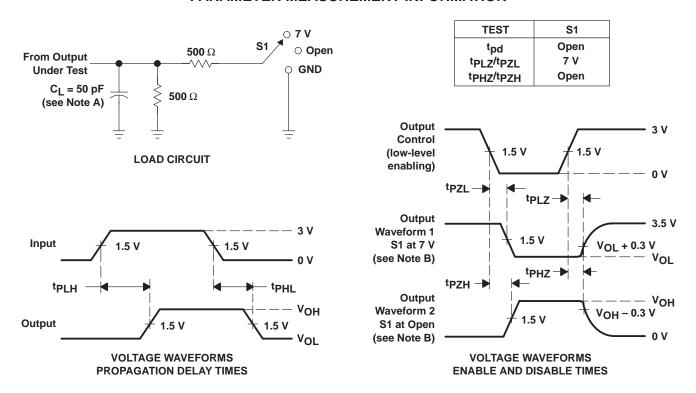
The propagation delay is based on the RC time constant of the typical on-state resistance of the switch and a load capacitance of 50 pF, when driven by an ideal voltage source (zero output impedance).



[‡] This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

[§] Measured by the voltage drop between A and B terminals at the indicated current through the switch. On-state resistance is determined by the lower of the voltages of the two (A or B) terminals.

PARAMETER MEASUREMENT INFORMATION



NOTES: A. CL includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_0 = 50 \,\Omega$, $t_f \leq$ 2.5 ns, $t_f \leq$ 2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. tpLZ and tpHZ are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. tpLH and tpHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms



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